

# ER-OLED1602-4 Series

## OLED Display Datasheet



## EastRising Technology Co., Limited

**Attention:**

- A. Some specifications of IC are not listed in this datasheet. Please refer to the IC datasheet for more details.
- B. The related documents for interfacing, demo code, ic datasheet are all available, please download from [www.buydisplay.com](http://www.buydisplay.com).
- C. Please pay more attention to "Quality Control" in this Datasheet. We assume you already agree with these criterions when you place an order with us. No more recommendations.

REV	DESCRIPTION	RELEASE DATE
1.0	Preliminary Release	Aug-01-2014

## ORDERING INFORMATION

Order Number

Part Number(Order Number)	Description
ER-OLED1602-4W	16x2 Character OLED Display Module in White Color
ER-OLED1602-4Y	16x2 Character OLED Display Module in Yellow Color
ER-DBO1602-4	Testing or Demo Board ER-OLED1602-4 Series Products

Image



↑ ER-OLED1602-4W



↑ ER-OLED1602-4Y

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## 1. Basic Specifications

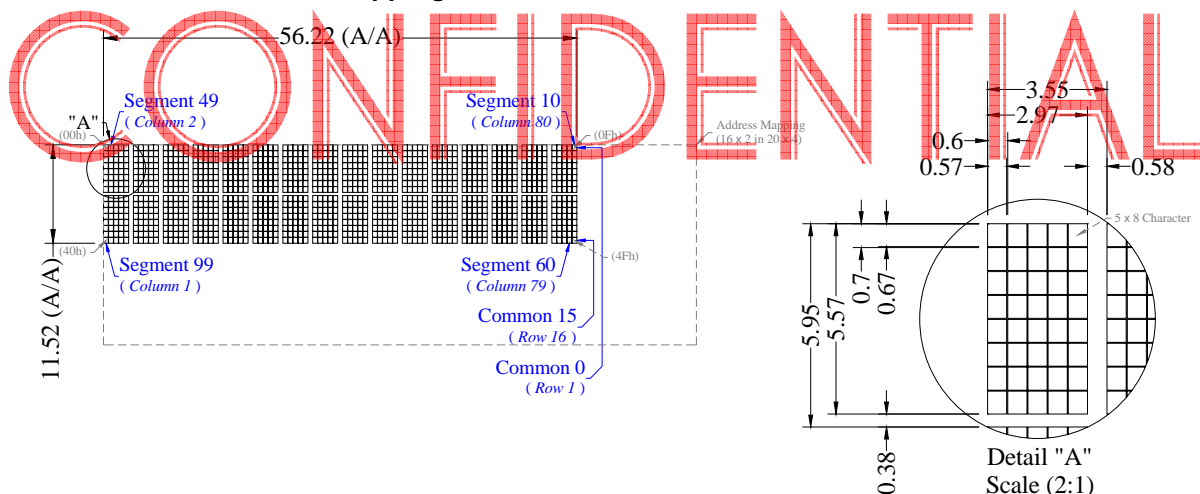
### 1.1 Display Specifications

- 1) Display Mode: Passive Matrix
- 2) Drive Duty: 1/16 Duty

### 1.2 Mechanical Specifications

- 1) Outline Drawing: According to the annexed outline drawing
- 2) Number of Characters: 16 Characters ( 5 × 8 ) × 2 Lines
- 3) Panel Size: 68.50 × 17.50 × 2.00 (mm)
- 4) Active Area: 56.22 × 11.52 (mm)
- 5) Character Pitch: 3.55 × 5.95 (mm)
- 6) Character Size: 2.97 × 5.57 (mm)
- 7) Pixel Pitch: 0.60 × 0.70 (mm)
- 8) Pixel Size: 0.57 × 0.67 (mm)
- 9) Weight: 4.98 (g)

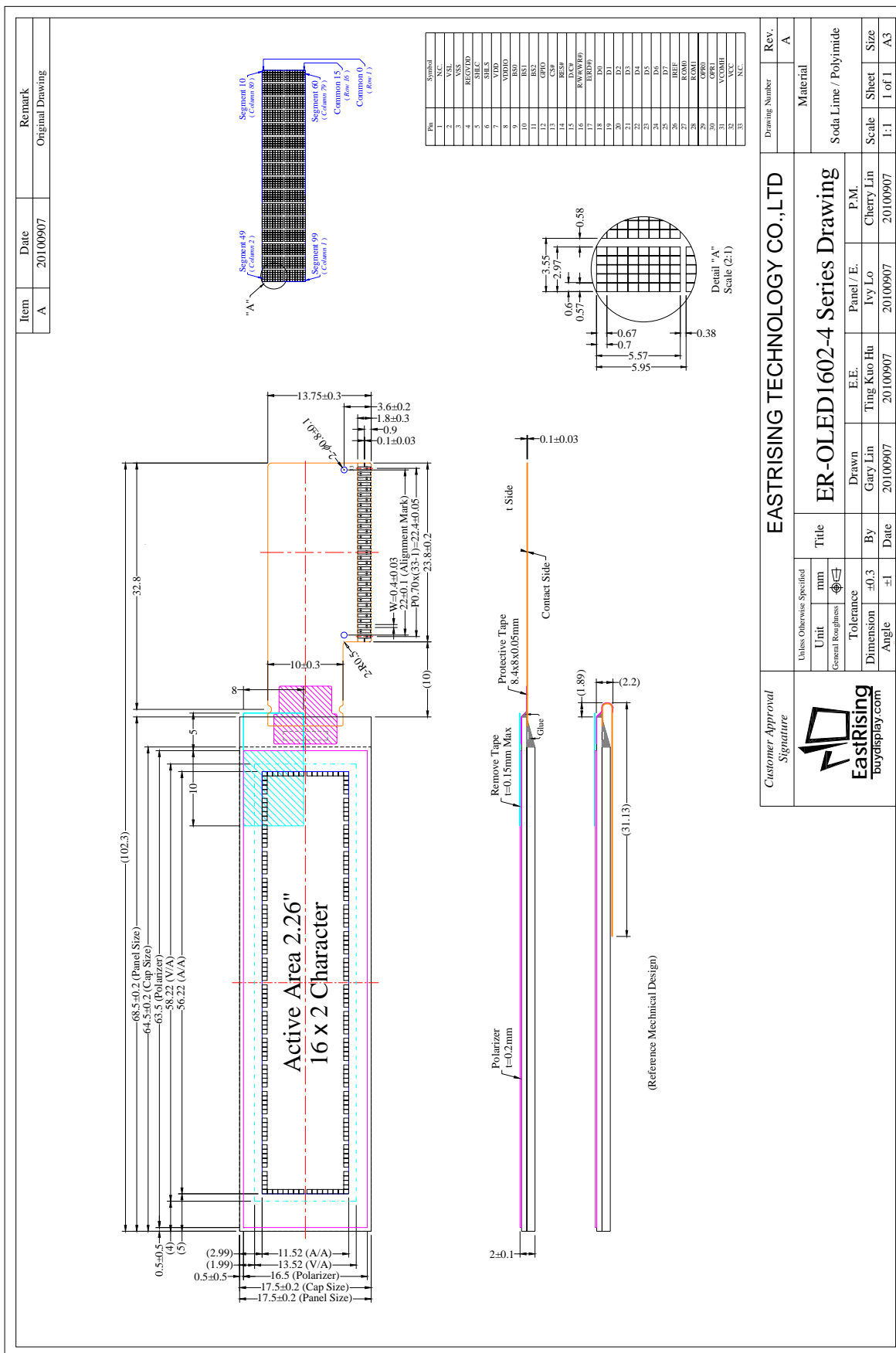
### 1.3 Active Area / Address Mapping & Character Construction



**Address Mapping**

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16
Line 1	00h	01h	02h	03h	04h	05h	06h	07h	08h	09h	0Ah	0Bh	0Ch	0Dh	0Eh	0Fh
Line 2	40h	41h	42h	43h	44h	45h	46h	47h	48h	49h	4Ah	4Bh	4Ch	4Dh	4Eh	4Fh

**1.4 Mechanical Drawing**



## 1.5 Pin Definition

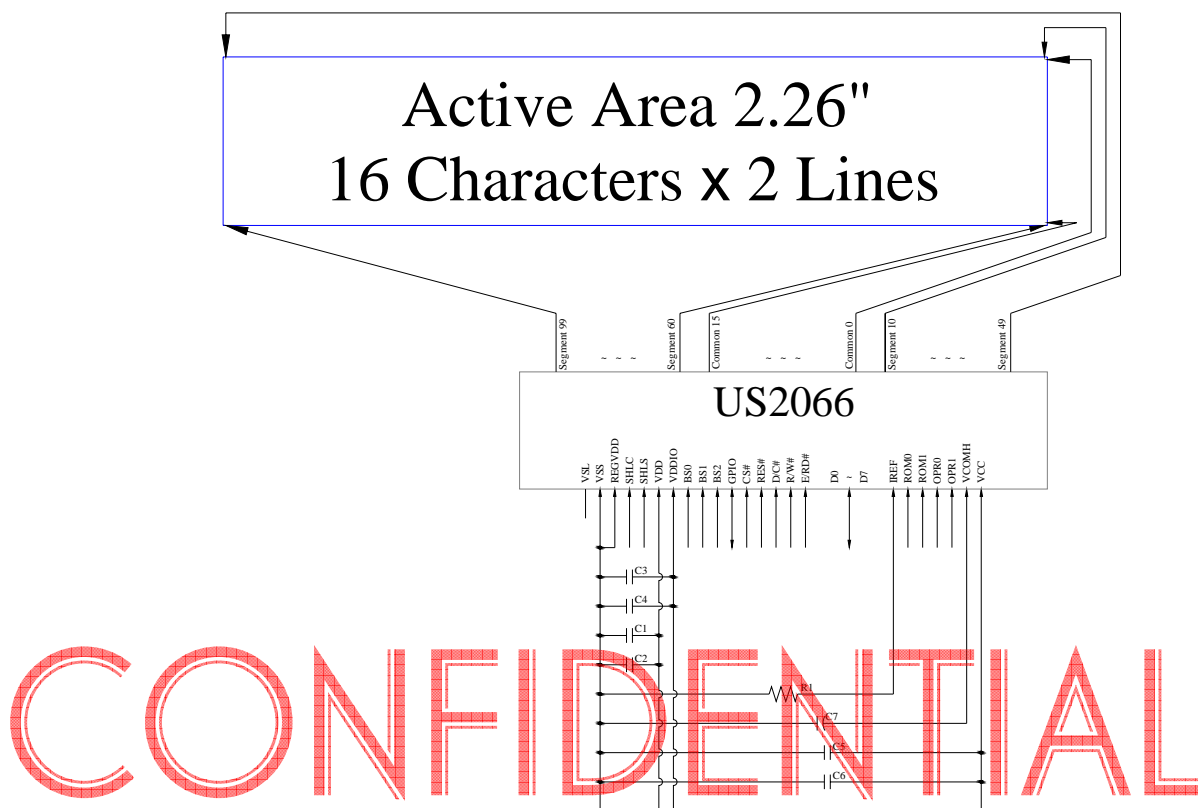
Pin Number	Symbol	I/O	Function															
Power Supply																		
7	VDD	P	<b>Power Supply for Logic Circuit</b> This is a voltage supply pin which is supplied externally or regulated internally. A capacitor should be connected between this pin and V <sub>SS</sub> under all circumstances. When internal V <sub>DD</sub> is disabled, this is a power input pin. It must be connected to V <sub>DDIO</sub> or external source and always be equal to or lower than V <sub>DDIO</sub> . (Low Voltage I/O Application) When internal V <sub>DD</sub> is enabled, it is regulated internally from V <sub>DDIO</sub> . (5V I/O Application)															
8	VDDIO	P	<b>Power Supply for Interface Logic Level</b> This is a voltage supply pin. It should match with the MCU interface voltage level and must be connected to external source															
3	VSS	P	<b>Ground of OEL System</b> This is a ground pin. It also acts as a reference for the logic pins, the OEL driving voltages, and the analog circuits. It must be connected to external ground.															
32	VCC	P	<b>Power Supply for OEL Panel</b> This is the most positive voltage supply pin of the chip. It must be connected to external source.															
Driver																		
26	IREF	I	<b>Current Reference for Brightness Adjustment</b> This pin is segment current reference pin. A resistor should be connected between this pin and V <sub>SS</sub> . Set the current at 15μA.															
31	VCOMH	P	<b>Voltage Output High Level for COM Signal</b> This pin is the input pin for the voltage output high level for COM signals. A capacitor should be connected between this pin and V <sub>SS</sub> .															
2	VSL	P	<b>Voltage Output Low Level for SEG Signal</b> This is segment voltage reference pin. When external V <sub>SL</sub> is not used, this pin should be left open. When external V <sub>SL</sub> is used, this pin should connect with resistor and diode to ground.															
External IC Communication																		
12	GPIO	I/O	<b>General Purpose Input/Output</b> This pin could be left open individually or have signal inputted/outputted. It is able to use as the external DC/DC converter circuit enabled/disabled control or other applications.															
Configuration																		
4	REGVDD	I	<b>5V I/O Regulator Configuration</b> This is internal V <sub>DD</sub> regulator selection pin in 5V I/O application mode. When this pin is pulled "Low", internal V <sub>DD</sub> regulator is disabled. (Low Voltage I/O Application) When this pin is pulled "High", internal V <sub>DD</sub> regulator is enabled. (5V I/O Application)															
5	SHLC	I	<b>Scanning Direction for COM Signal</b> This pin is used to determine COM output scanning direction. It can still be programmable and defined by fundamental command.															
6	SHLS	I	<b>Mapping Direction for SEG Signal</b> This pin is used to change the mapping between the display data column address and the segment driver. It can still be programmable and defined by fundamental command.															
27 28	ROM0 ROM1	I	<b>Built-in Character ROM Selection</b> These pins are used to select the appropriate character ROM. See the following table & Section 4.5: <table><tr><td></td><td>ROM0</td><td>ROM1</td></tr><tr><td>ROM A (Page 19)</td><td>0</td><td>0</td></tr><tr><td>ROM B (Page 20)</td><td>1</td><td>0</td></tr><tr><td>ROM C (Page 21)</td><td>0</td><td>1</td></tr><tr><td>Software Selectable</td><td>1</td><td>1</td></tr></table> It can still be programmable and defined by extended command.		ROM0	ROM1	ROM A (Page 19)	0	0	ROM B (Page 20)	1	0	ROM C (Page 21)	0	1	Software Selectable	1	1
	ROM0	ROM1																
ROM A (Page 19)	0	0																
ROM B (Page 20)	1	0																
ROM C (Page 21)	0	1																
Software Selectable	1	1																

## 1.5 Pin Definition (Continued)

Pin Number	Symbol	I/O	Function																												
<b>Configuration (Continued)</b>																															
29 30	OPR0 OPR1	I	<b>Character ROM/RAM Management</b> These pins are used to manage the character number of character generator. See the following table & Section 4.6: <table border="1"> <thead> <tr> <th>CGROM</th><th>CGRAM</th><th>OPR0</th><th>OPR1</th></tr> </thead> <tbody> <tr> <td>240</td><td>8</td><td>0</td><td>0</td></tr> <tr> <td>248</td><td>8</td><td>1</td><td>0</td></tr> <tr> <td>250</td><td>6</td><td>0</td><td>1</td></tr> <tr> <td>256</td><td>0</td><td>1</td><td>1</td></tr> </tbody> </table> It can still be programmable and defined by extended command.	CGROM	CGRAM	OPR0	OPR1	240	8	0	0	248	8	1	0	250	6	0	1	256	0	1	1								
CGROM	CGRAM	OPR0	OPR1																												
240	8	0	0																												
248	8	1	0																												
250	6	0	1																												
256	0	1	1																												
<b>Interface</b>																															
9 10 11	BS0 BS1 BS2	I	<b>Communicating Protocol Selection</b> These pins are MCU interface selection input. See the following table: <table border="1"> <thead> <tr> <th></th><th>BS0</th><th>BS1</th><th>BS2</th></tr> </thead> <tbody> <tr> <td>I<sup>2</sup>C</td><td>0</td><td>1</td><td>0</td></tr> <tr> <td>SPI</td><td>0</td><td>0</td><td>0</td></tr> <tr> <td>4-bit 68XX Parallel</td><td>1</td><td>0</td><td>1</td></tr> <tr> <td>4-bit 80XX Parallel</td><td>1</td><td>1</td><td>1</td></tr> <tr> <td>8-bit 68XX Parallel</td><td>0</td><td>0</td><td>1</td></tr> <tr> <td>8-bit 80XX Parallel</td><td>0</td><td>1</td><td>1</td></tr> </tbody> </table>		BS0	BS1	BS2	I <sup>2</sup> C	0	1	0	SPI	0	0	0	4-bit 68XX Parallel	1	0	1	4-bit 80XX Parallel	1	1	1	8-bit 68XX Parallel	0	0	1	8-bit 80XX Parallel	0	1	1
	BS0	BS1	BS2																												
I <sup>2</sup> C	0	1	0																												
SPI	0	0	0																												
4-bit 68XX Parallel	1	0	1																												
4-bit 80XX Parallel	1	1	1																												
8-bit 68XX Parallel	0	0	1																												
8-bit 80XX Parallel	0	1	1																												
14	RES#	I	<b>Power Reset for Controller and Driver</b> This pin is reset signal input. When the pin is low, initialization of the chip is executed.																												
13	CS#	I	<b>Chip Select</b> This pin is the chip select input. The chip is enabled for MCU communication only when CS# is pulled low.																												
15	D/C#	I	<b>Data/Command Control</b> This pin is Data/Command control pin. When the pin is pulled high, the input at D7~D0 is treated as display data. When the pin is pulled low, the input at D7~D0 will be transferred to the command register. For detail relationship to MCU interface signals, please refer to the Timing Characteristics Diagrams. When the pin is pulled high and serial interface mode is selected, the data at SDIN is treated as data. When it is pulled low, the data at SDIN will be transferred to the command register. In I <sup>2</sup> C mode, this pin acts as SA0 for slave address selection.																												
17	E/RD#	I	<b>Read/Write Enable or Read</b> This pin is MCU interface input. When interfacing to a 68XX-series microprocessor, this pin will be used as the Enable (E) signal. Read/write operation is initiated when this pin is pulled high and the CS# is pulled low. When connecting to an 80XX-microprocessor, this pin receives the Read (RD#) signal. Data read operation is initiated when this pin is pulled low and CS# is pulled low.																												
16	R/W#	I	<b>Read/Write Select or Write</b> This pin is MCU interface input. When interfacing to a 68XX-series microprocessor, this pin will be used as Read/Write (R/W#) selection input. Pull this pin to "High" for read mode and pull it to "Low" for write mode. When 80XX interface mode is selected, this pin will be the Write (WR#) input. Data write operation is initiated when this pin is pulled low and the CS# is pulled low.																												
18~25	D0~D7	I/O	<b>Host Data Input/Output Bus</b> These pins are 8-bit bi-directional data bus to be connected to the microprocessor's data bus. When serial mode is selected, D1 will be the serial data input SDIN and D0 will be the serial clock input SCLK. When I <sup>2</sup> C mode is selected, D2, D1 should be tied together and serve as SDA <sub>OUT</sub> , SDA <sub>IN</sub> in application and D0 is the serial clock input, SCL.																												
<b>Reserve</b>																															
1, 33	N.C. (GND)	-	<b>Reserved Pin (Supporting Pin)</b> The supporting pins can reduce the influences from stresses on the function pins. These pins must be connected to external ground as the ESD protection circuit.																												

## 1.6 Block Diagram

### 1.6.1 Low Voltage I/O Application



MCU Interface Selection: BS0, BS1 and BS2

Pins connected to MCU interface: CS#, RES#, D/C#, R/W#, E/RD#, and D0~D7

\* SHLC, SHLC, ROM0, ROM1, OPR0 and OPR1 should be configured.

C1, C3, C5: 0.1μF

C2, C4: 4.7μF

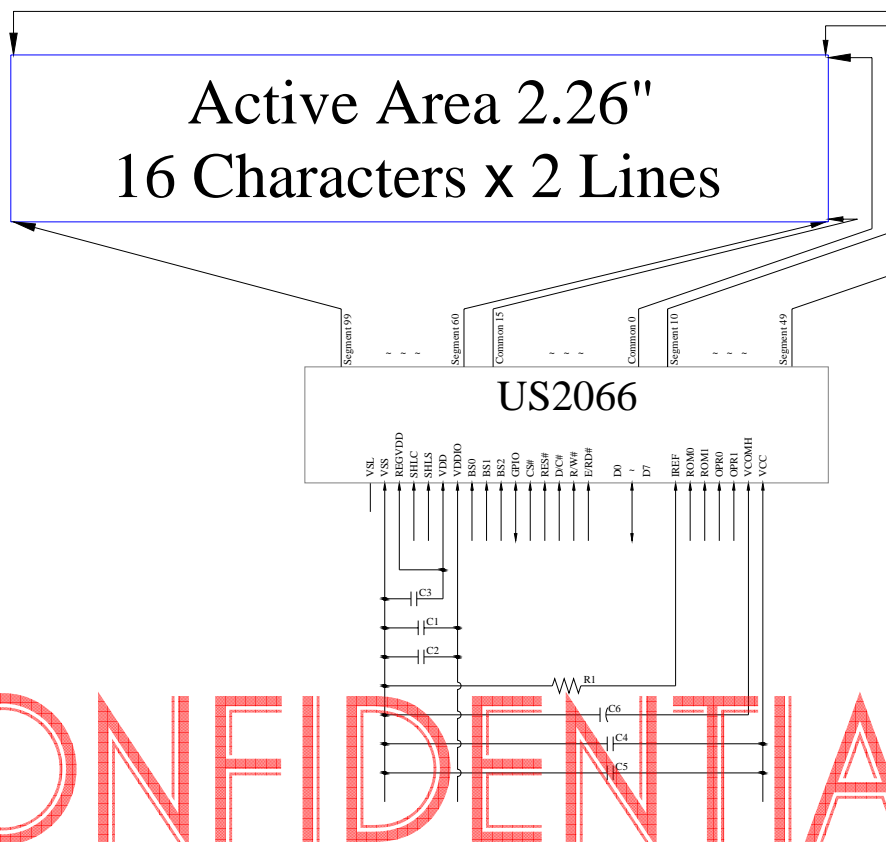
C6: 10μF

C7: 4.7μF / 25V Tantalum Capacitor

R1: 470kΩ, R1 = (Voltage at IREF - VSS) / IREF



### 1.6.2 5V I/O Application



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MCU Interface Selection: BS0, BS1 and BS2

Pins connected to MCU interface: CS#, RES#, D/C#, R/W#, E/RD#, and D0~D7

\* SHLC, SHLC, ROM0, ROM1, OPR0 and OPR1 should be configured.

C1, C4: 0.1μF

C2: 4.7μF

C3: 1μF

C5: 10μF

C6: 4.7μF / 25V Tantalum Capacitor

R1: 470kΩ,  $R1 = (\text{Voltage at IREF} - VSS) / IREF$

## 2. Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit	Notes
Supply Voltage for Logic	$V_{DD}$	-0.3	6	V	1, 2
Supply Voltage for I/O Pins	$V_{DDIO}$	-0.3	6	V	1, 2
Supply Voltage for Display	$V_{CC}$	0	15	V	1, 2
Operating Temperature	$T_{OP}$	-40	85	°C	3
Storage Temperature	$T_{STG}$	-40	90	°C	3
Life Time (120 cd/m <sup>2</sup> )		30,000	-	hour	4

Note 1: All the above voltages are on the basis of " $V_{SS} = 0V$ ".

Note 2: When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. Also, for normal operations, it is desirable to use this module under the conditions according to Section 3. "Optics & Electrical Characteristics". If this module is used beyond these conditions, malfunctioning of the module can occur and the reliability of the module may deteriorate.

Note 3: The defined temperature ranges do not include the polarizer. The maximum withstood temperature of the polarizer should be 80°C.

Note 4:  $V_{CC} = 12.0V$ ,  $T_a = 25^\circ C$ , 50% Checkerboard.

Software configuration follows Section 4.4 Initialization.

End of lifetime is specified as 50% of initial brightness reached. The average operating lifetime at room temperature is estimated by the accelerated operation at high temperature conditions.

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### 3. Optics & Electrical Characteristics

#### 3.1 Optics Characteristics

Characteristics	Symbol	Conditions	Min	Typ	Max	Unit
Brightness	$L_{br}$	Note 5	100	120	-	cd/m <sup>2</sup>
C.I.E. (White)	(x) (y)	C.I.E. 1931	0.25 0.27	0.29 0.31	0.33 0.35	
Dark Room Contrast	CR		-	>10,000:1	-	
Viewing Angle			-	Free	-	degree

\* Optical measurement taken at  $V_{DD} = 2.8V$  or  $5.0V$ ,  $V_{CC} = 12.0V$ .  
Software configuration follows Section 4.4 Initialization.

#### 3.2 DC Characteristics

Characteristics	Symbol	Conditions	Min	Typ	Max	Unit
Supply Voltage for Logic	$V_{DD}$	(Low Voltage I/O Application)	2.4	2.8	$V_{DDIO}$	V
Supply Voltage for I/O Pins	$V_{DDIO}$		2.4	2.8	3.6	V
Supply Voltage for Logic	$V_{DD}$	(5V I/O Application)	-	-	-	V
Supply Voltage for I/O Pins	$V_{DDIO}$		4.4	5.0	5.5	V
Supply Voltage for Display	$V_{CC}$	Note 5	11.5	12.0	12.5	V
High Level Input	$V_{IH}$	$I_{OUT} = 100\mu A, 3.3MHz$	$0.8 \times V_{DDIO}$	-	$V_{DDIO}$	V
Low Level Input	$V_{IL}$	$I_{OUT} = 100\mu A, 3.3MHz$	0	-	$0.2 \times V_{DDIO}$	V
High Level Output	$V_{OH}$	$I_{OUT} = 100\mu A, 3.3MHz$	$0.9 \times V_{DDIO}$	-	$V_{DDIO}$	V
Low Level Output	$V_{OL}$	$I_{OUT} = 100\mu A, 3.3MHz$	0	-	$0.1 \times V_{DDIO}$	V
Operating Current for $V_{DD}$	$I_{DD}$		-	180	300	$\mu A$
Operating Current for $V_{CC}$	$I_{CC}$	Note 6	-	12.0	15.0	mA
		Note 7	-	18.0	22.1	mA
		Note 8	-	33.0	40.0	mA
Sleep Mode Current for $V_{DD}$	$I_{DD, SLEEP}$		-	1	10	$\mu A$
Sleep Mode Current for $V_{CC}$	$I_{CC, SLEEP}$		-	2	10	$\mu A$

Note 5: Brightness ( $L_{br}$ ) and Supply Voltage for Display ( $V_{CC}$ ) are subject to the change of the panel characteristics and the customer's request.

Note 6:  $V_{DD} = 2.8V$  or  $5.0V$ ,  $V_{CC} = 9.0V$ , 30% Display Area Turn on.

Note 7:  $V_{DD} = 2.8V$  or  $5.0V$ ,  $V_{CC} = 9.0V$ , 50% Display Area Turn on.

Note 8:  $V_{DD} = 2.8V$  or  $5.0V$ ,  $V_{CC} = 9.0V$ , 100% Display Area Turn on.

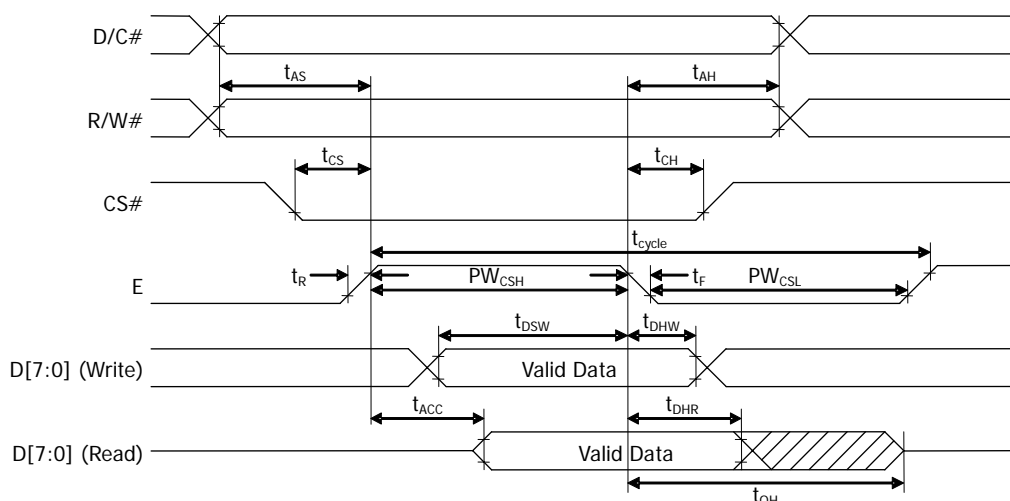
\* Software configuration follows Section 4.4 Initialization.

### 3.3 AC Characteristics

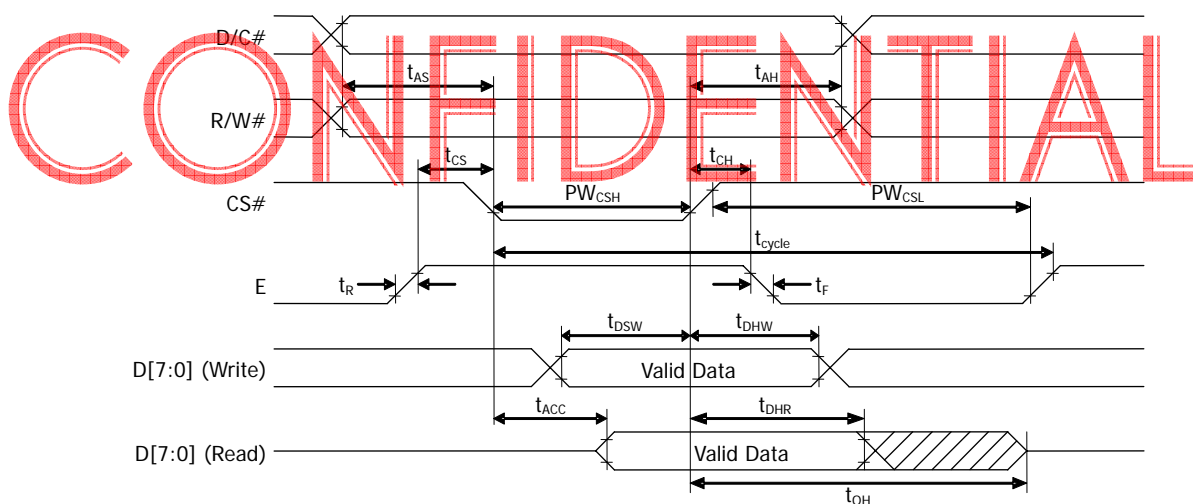
#### 3.3.1 68XX-Series MPU Parallel Interface Timing Characteristics:

Symbol	Description	Min	Max	Unit
$t_{\text{cycle}}$	Clock Cycle Time (Write Cycle)	400	-	ns
$t_{\text{AS}}$	Address Setup Time	13	-	ns
$t_{\text{AH}}$	Address Hold Time	17	-	ns
$t_{\text{DSW}}$	Write Data Setup Time	35	-	ns
$t_{\text{DHW}}$	Write Data Hold Time	18	-	ns
$t_{\text{DHR}}$	Read Data Hold Time	13	-	ns
$t_{\text{OH}}$	Output Disable Time	10	90	ns
$t_{\text{ACC}}$	Access Time (RAM)	-	125	ns
	Access Time (Command)			
$t_{\text{CS}}$	Chip Select Time	0	-	ns
$t_{\text{CH}}$	Chip Select Hold Time	0	-	ns
$PW_{\text{CSL}}$	Chip Select Low Pulse Width (Read RAM)	250	-	ns
	Chip Select Low Pulse Width (Read Command)	250		
	Chip Select Low Pulse width (Write)	50		
$PW_{\text{CSH}}$	Chip Select High Pulse Width (Read)	155	-	ns
	Chip Select High Pulse Width (Write)	55		
$t_{\text{R}}$	Rise Time	-	15	ns
$t_{\text{F}}$	Fall Time	-	15	ns

\* ( $V_{\text{DDIO}} - V_{\text{SS}} = 2.4\text{V to } 3.6\text{V} / 4.4\text{V to } 5.5\text{V}$ ,  $T_a = 25^\circ\text{C}$ )



( CS# "Low Pulse Width" > E "High Pulse Width" )

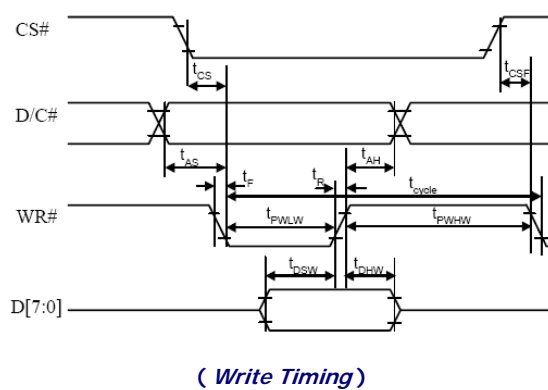
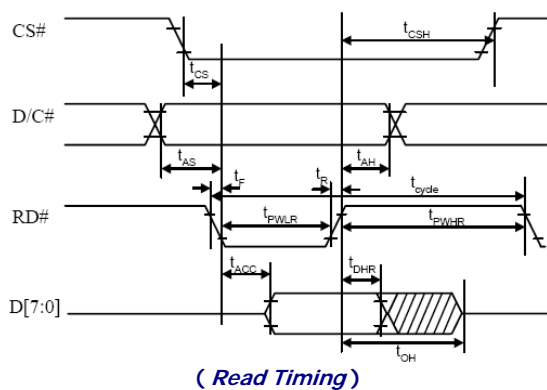


( CS# "Low Pulse Width" < E "High Pulse Width" )

## 3.3.2 80XX-Series MPU Parallel Interface Timing Characteristics:

Symbol	Description	Min	Max	Unit
$t_{cycle}$	Clock Cycle Time (Write Cycle)	400	-	ns
$t_{AS}$	Address Setup Time	13	-	ns
$t_{AH}$	Address Hold Time	17	-	ns
$t_{DSW}$	Write Data Setup Time	35	-	ns
$t_{DHW}$	Write Data Hold Time	18	-	ns
$t_{DHR}$	Read Data Hold Time	13	-	ns
$t_{OH}$	Output Disable Time	10	70	ns
$t_{ACC}$	Access Time (RAM)	-	125	ns
	Access Time (Command)			
$t_{CS}$	Chip Select Time	0	-	ns
$t_{CSH}$	Chip Select Hold Time to Read Signal	0	-	ns
$t_{CSF}$	Chip Select Hold Time	0	-	ns
	Chip Select Low Pulse Width (Read RAM) - $t_{PWLR}$	250	-	ns
$PW_{CSL}$	Chip Select Low Pulse Width (Read Command) - $t_{PWLR}$	250		
	Chip Select Low Pulse width (Write) - $t_{PWLW}$	50		
	Chip Select High Pulse Width (Read) - $t_{PWHR}$	155	-	ns
$PW_{CSH}$	Chip Select High Pulse Width (Write) - $t_{PWHW}$	55		
$t_R$	Rise Time	-	15	ns
$t_F$	Fall Time	-	15	ns

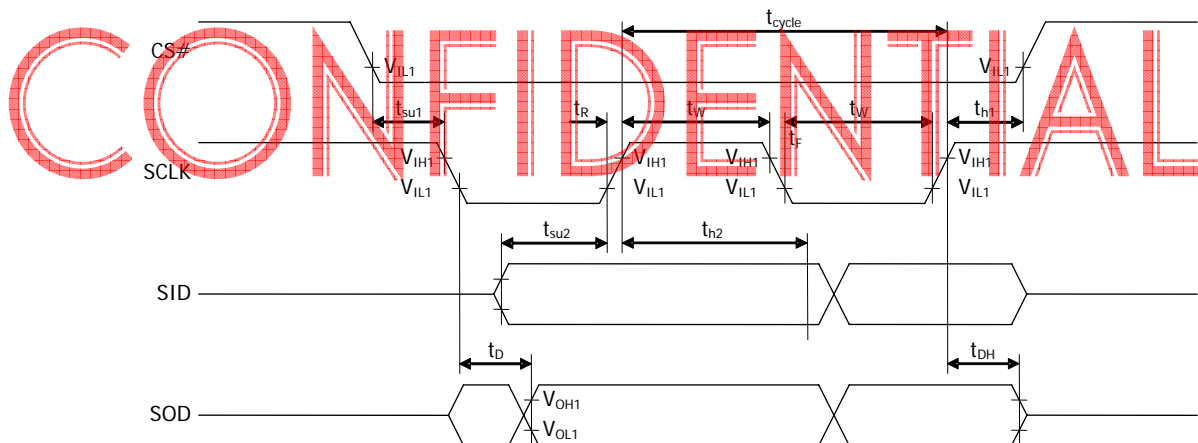
\* ( $V_{DDIO} - V_{SS} = 2.4V$  to  $3.6V$  /  $4.4V$  to  $5.5V$ ,  $T_a = 25^\circ C$ )



### 3.3.3 Serial Interface Timing Characteristics:

Symbol	Description	Min	Max	Unit
$t_{cycle}$	Serial Clock Cycle Time	1	20	ns
$t_{su1}$	Chip Select Setup Time	60	-	ns
$t_{h1}$	Chip Select Hold Time	20	-	ns
$t_{su2}$	Serial Input Data Setup Time	200	-	ns
$t_{h2}$	Serial Input Data Hold Time	TBD	-	ns
$t_D$	Serial Output Data Delay Time	-	TBD	ns
$t_{DH}$	Serial Output Data Hold Time	10	-	ns
$t_W$	Serial Clock Width (Low, High)	400	-	ns
$t_R$	Serial Clock Rise Time	-	15	ns
$t_F$	Serial Clock Fall Time	-	15	ns

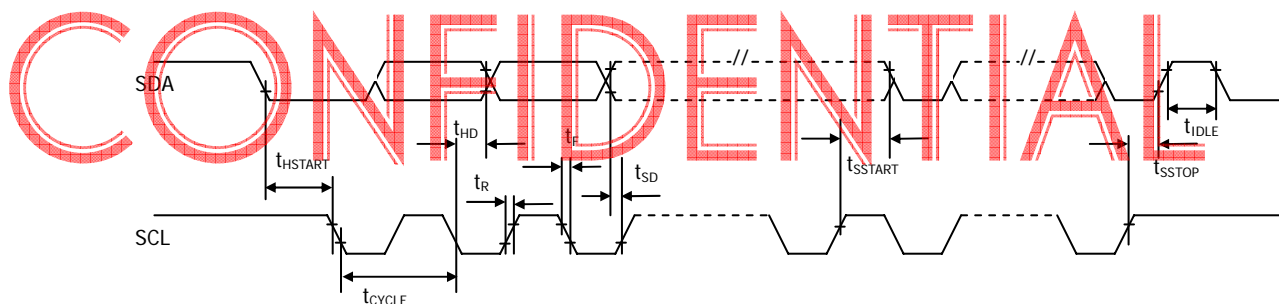
\* ( $V_{DDIO} - V_{SS} = 2.4V$  to  $3.6V$  /  $4.4V$  to  $5.5V$ ,  $T_a = 25^\circ C$ )



3.3.4 I<sup>2</sup>C Interface Timing Characteristics:

Symbol	Description	Min	Max	Unit
t <sub>cycle</sub>	Clock Cycle Time	2.5	-	μs
t <sub>HSTART</sub>	Start Condition Hold Time	0.6	-	μs
t <sub>HD</sub>	Data Hold Time (for "SDA <sub>OUT</sub> " Pin)	5	-	ns
	Data Hold Time (for "SDA <sub>IN</sub> " Pin)	300		
t <sub>SD</sub>	Data Setup Time	100	-	ns
t <sub>SSTART</sub>	Start Condition Setup Time (Only relevant for a repeated Start condition)	0.6	-	μs
t <sub>SSTOP</sub>	Stop Condition Setup Time	0.6	-	μs
t <sub>R</sub>	Rise Time for Data and Clock Pin		300	ns
t <sub>F</sub>	Fall Time for Data and Clock Pin		300	ns
t <sub>IDLE</sub>	Idle Time before a New Transmission can Start	1.3	-	μs

\* (V<sub>DDIO</sub> - V<sub>SS</sub> = 2.4V to 3.6V / 4.4V to 5.5V, T<sub>a</sub> = 25°C)





## 4. Functional Specification

### 4.1 Commands

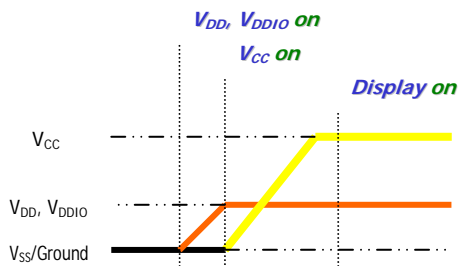
Refer to the Technical Manual for the US2066

### 4.2 Power down and Power up Sequence

To protect OEL panel and extend the panel life time, the driver IC power up/down routine should include a delay period between high voltage and low voltage power sources during turn on/off. It gives the OEL panel enough time to complete the action of charge and discharge before/after the operation.

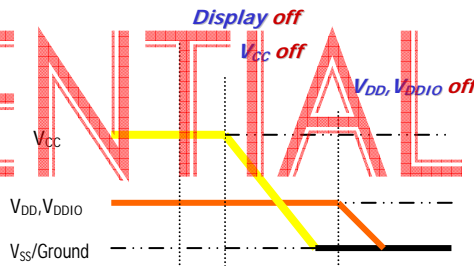
#### 4.2.1 Power up Sequence:

1. Power up  $V_{DD}$  &  $V_{DDIO}$
2. Send Display off command
3. Initialization
4. Clear Screen
5. Power up  $V_{CC}$
6. Delay 100ms  
(When  $V_{CC}$  is stable)
7. Send Display on command



#### 4.2.2 Power down Sequence:

1. Send Display off command
2. Power down  $V_{CC}$
3. Delay 100ms  
(When  $V_{CC}$  is reach 0 and panel is completely discharges)
4. Power down  $V_{DD}$  &  $V_{DDIO}$



Note 9:

- 1) Since an ESD protection circuit is connected between  $V_{DD}$ ,  $V_{DDIO}$  and  $V_{CC}$  inside the driver IC,  $V_{CC}$  becomes lower than  $V_{DD}$  &  $V_{DDIO}$  whenever  $V_{DD}$  &  $V_{DDIO}$  is ON and  $V_{CC}$  is OFF.
- 2)  $V_{CC}$  should be kept float (disable) when it is OFF.
- 3) Power Pins ( $V_{DD}$ ,  $V_{DDIO}$ ,  $V_{CC}$ ) can never be pulled to ground under any circumstance.
- 4)  $V_{DD}$  &  $V_{DDIO}$  should not be power down before  $V_{CC}$  power down.

### 4.3 Reset Circuit

When RES# input is low, the chip is initialized with the following status:

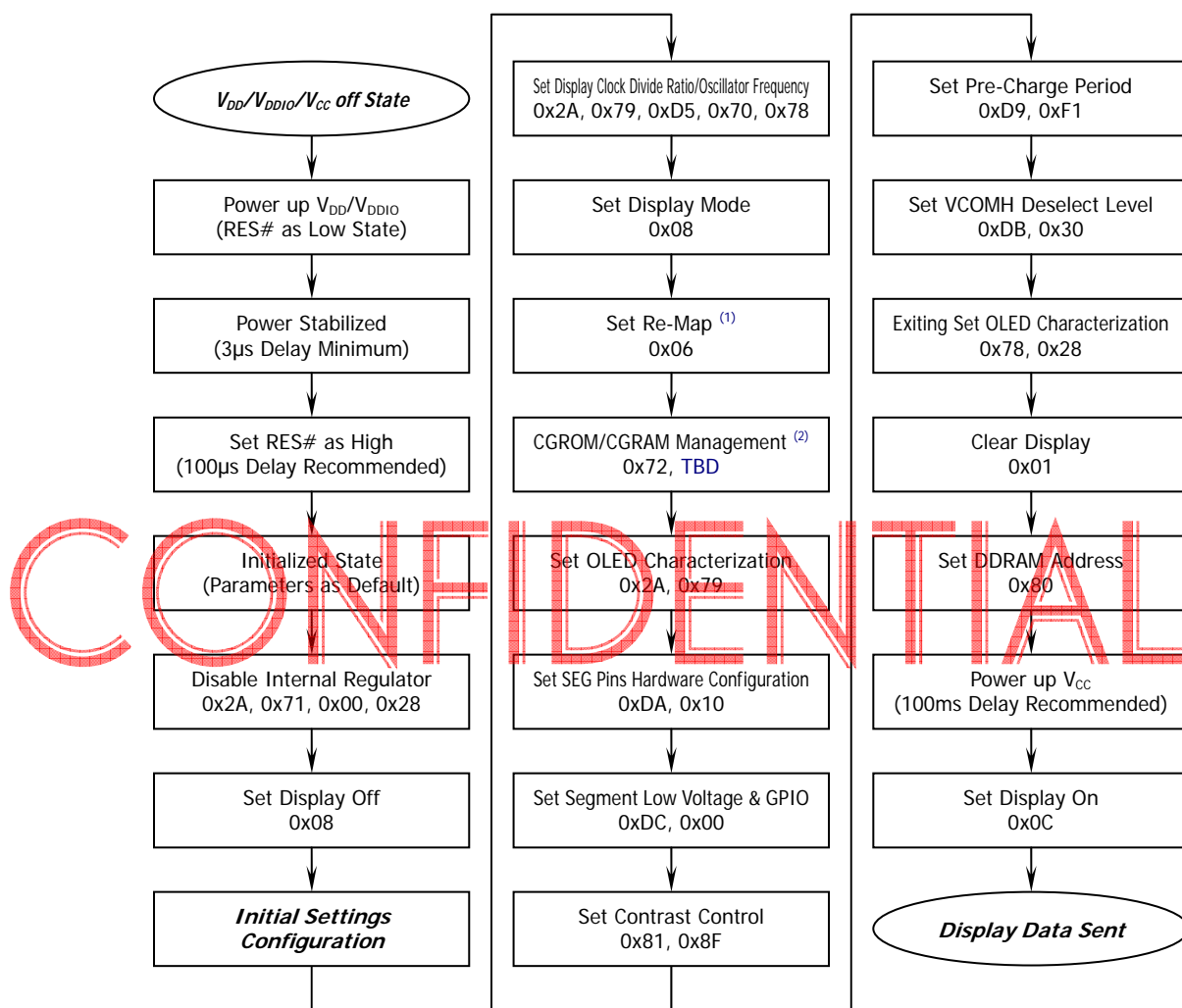
1. Display is OFF
2. 5×8 Character Mode
3. Display start position is set at display RAM address 0
4. CGRAM address counter is set at 0
5. Cursor is OFF
6. Blink is OFF
7. Contrast control register is set at 7Fh
8. OLED command set is disabled

#### 4.4 Actual Application Example

Command usage and explanation of an actual example

##### 4.4.1 Low Voltage I/O Application

<Power up Sequence>

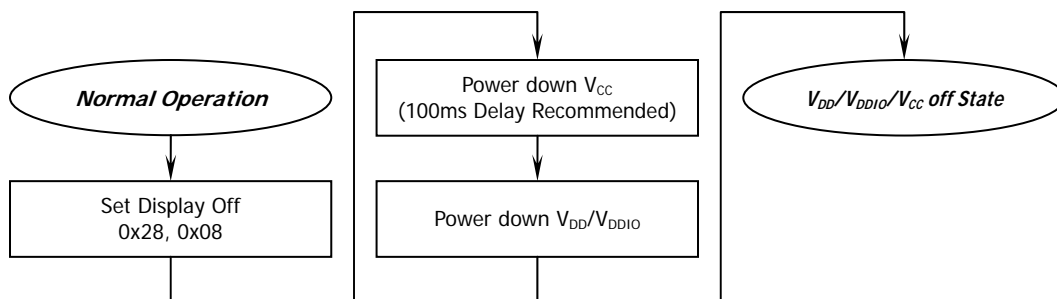


(1) This command could be programmable or defined by pin configuration.

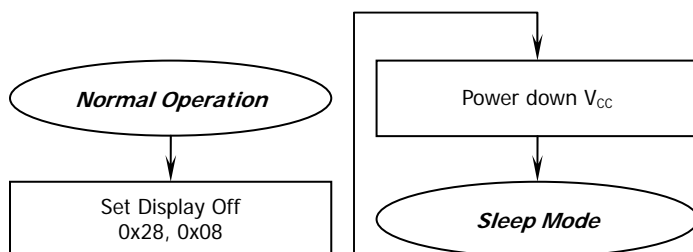
(2) This command could be programmable or defined by pin configuration. The written value of the parameter should depend on the selection from Section 4.5 & 4.6

If the noise is accidentally occurred at the displaying window during the operation, please reset the display in order to recover the display function.

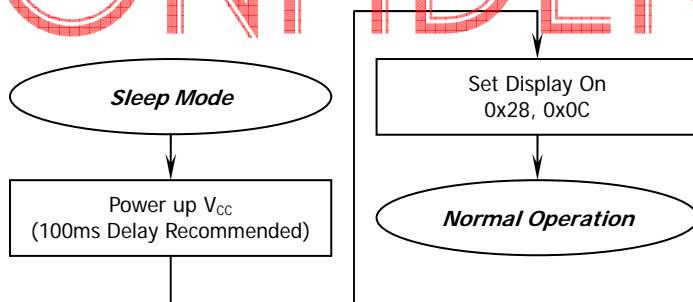
<Power down Sequence>



<Entering Sleep Mode>



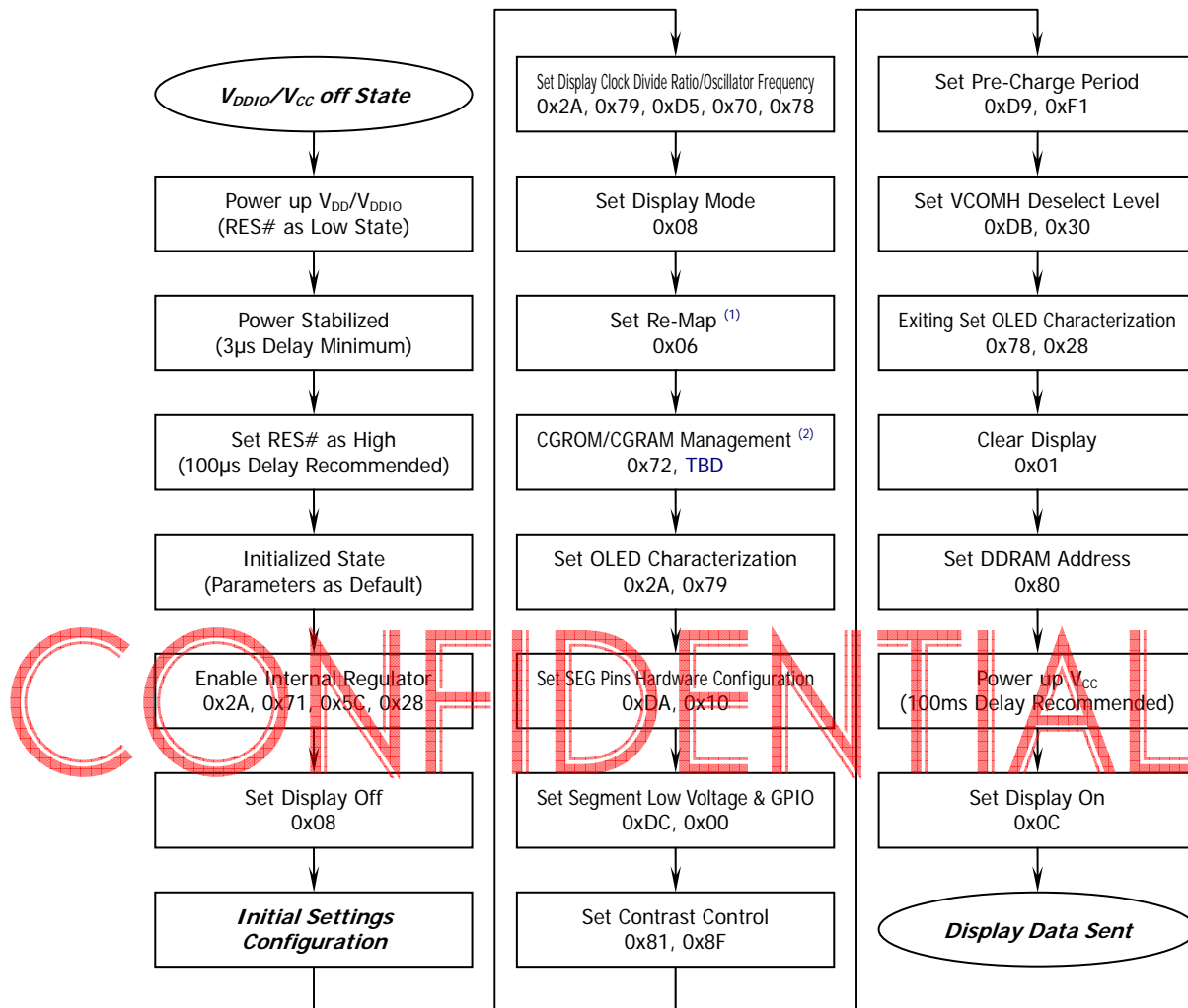
<Exiting Sleep Mode>



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#### 4.4.2 5V I/O Application

##### <Power up Sequence>

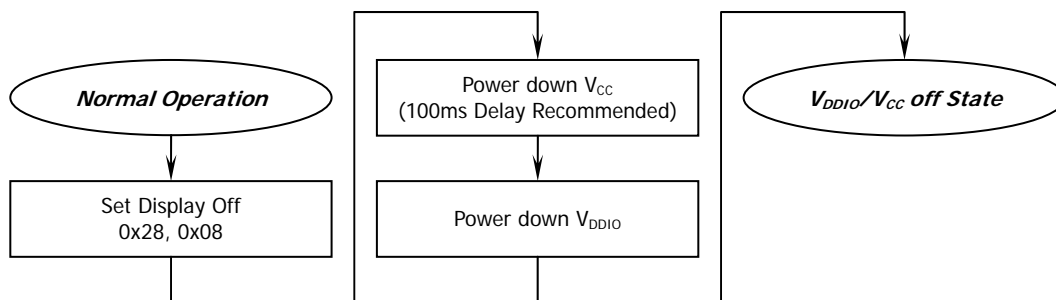


(1) This command could be programmable or defined by pin configuration.

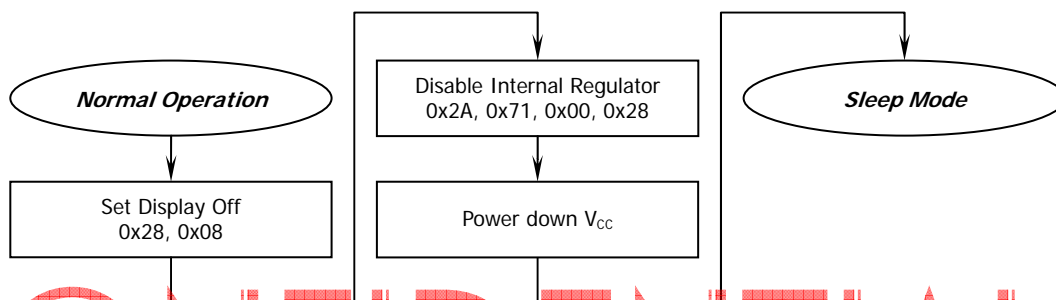
(2) This command could be programmable or defined by pin configuration. The written value of the parameter should depend on the selection from Section 4.5 & 4.6

If the noise is accidentally occurred at the displaying window during the operation, please reset the display in order to recover the display function.

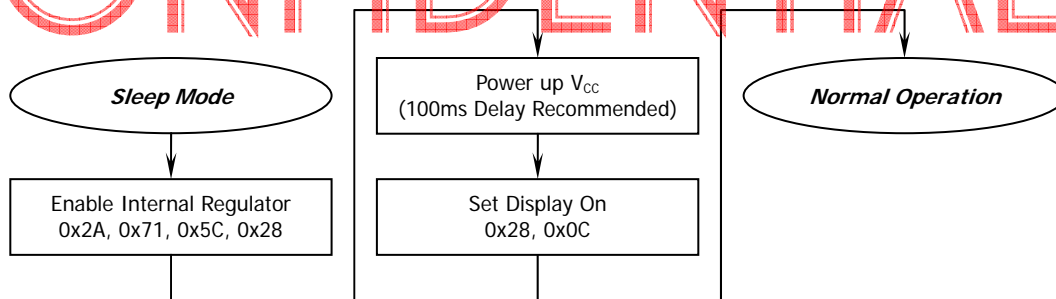
*<Power down Sequence>*



*<Entering Sleep Mode>*



*<Exiting Sleep Mode>*



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#### 4.5 Built-in CGROM (Character Generator ROM)

ROM A (ROM[1:0] = [0:0])

b3~0	b7~4	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111
0000																	
0001																	
0010																	
0011																	
0100																	
0101																	
0110																	
0111																	
1000																	
1001																	
1010																	
1011																	
1100																	
1101																	
1110																	
1111																	

**Language:** English, Irish, Spanish, Dutch (2), Danish, Norwegian, Swedish, Finnish, Czech (7), Slovene, Hungarian (2), Turkish (1)

The number in the parentheses is showing how many letters might be needed to build and define additionally at CGRAM. The darker background is showing the maximum addresses (00h~07h) those could be allocated by OPR[1:0] setting.



ROM B (ROM[1:0] = [0:1])

b7~4 b3~0	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111
0000																
0001																
0010																
0011																
0100																
0101																
0110																
0111																
1000																
1001																
1010																
1011																
1100																
1101																
1110																
1111																

**Language:** English, Irish, Portuguese, Spanish, French (1), Italian, German, Dutch (2), Icelandic, Danish, Norwegian, Swedish, Polish (8), Czech (8), Hungarian (2), Romanian (5), Turkish, Vietnamese (6), Russian (Small Letters)  
The number in the parentheses is showing how many letters might be needed to build and define additionally at CGRAM. The darker background is showing the maximum addresses (00h~07h) those could be allocated by OPR[1:0] setting.



ROM C (ROM[1:0] = [1:0])

b7-a b3-0	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111
0000																
0001																
0010																
0011																
0100																
0101																
0110																
0111																
1000																
1001																
1010																
1011																
1100																
1101																
1110																
1111																

Language: English, Dutch (2), Japanese, Greek (Small Letters)

The number in the parentheses is showing how many letters might be needed to build and define additionally at CGRAM. The darker background is showing the maximum addresses (00h~07h) those could be allocated by OPR[1:0] setting.



#### 4.6 Self-Defined CGRAM (Character Generator RAM)

8 Addresses Available for Self-Defined Characters (OPR[1:0] = [0:0])

b7~4	b3~0	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111
0000																	
0001																	

8 Addresses Available for Self-Defined Characters (OPR[1:0] = [0:1])

b7~4	b3~0	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111
0000																	
0001																	

6 Addresses Available for Self-Defined Characters (OPR[1:0] = [1:0])

b7~4	b3~0	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111
0000																	
0001																	

0 Address Available for Self-Defined Characters (OPR[1:0] = [1:1])

b7~4	b3~0	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111
0000																	
0001																	

## 5. Reliability

### 5.1 Contents of Reliability Tests

Item	Conditions	Criteria
High Temperature Operation	85°C, 240 hrs	The operational functions work.
Low Temperature Operation	-40°C, 240 hrs	
High Temperature Storage	90°C, 240 hrs	
Low Temperature Storage	-40°C, 240 hrs	
High Temperature/Humidity Operation	60°C, 90% RH, 240 hrs	
Thermal Shock	-40°C ⇔ 85°C, 100 cycles 60 mins dwell	

\* The samples used for the above tests do not include polarizer.

\* No moisture condensation is observed during tests.

### 5.2 Failure Check Standard

After the completion of the described reliability test, the samples were left at room temperature for 2 hrs prior to conducting the failure test at 23±5°C; 55±15% RH.

## 6. QUALITY CONTROL

### 6.1 EastRising Environment Required

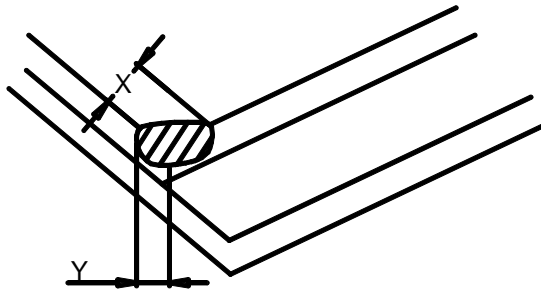
Customer's test & measurement are required to be conducted under the following conditions:

Temperature:	$23 \pm 5^{\circ}\text{C}$
Humidity:	$55 \pm 15\% \text{ RH}$
Fluorescent Lamp:	30W
Distance between the Panel & Lamp:	$\geq 50\text{cm}$
Distance between the Panel & Eyes of the Inspector:	$\geq 30\text{cm}$
Finger glove (or finger cover) must be worn by the inspector.	
Inspection table of jig must be anti-electrostatic.	

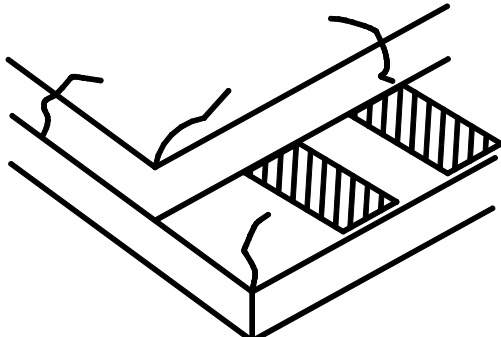

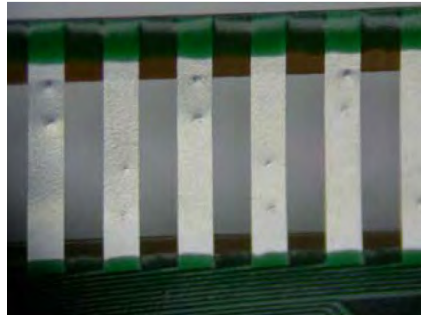
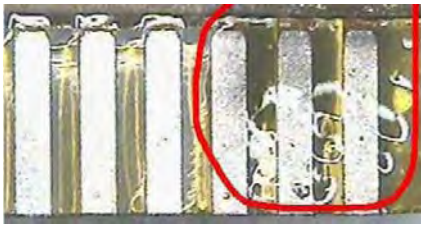
### 6.2 EastRising OLED Display Criteria & Acceptable Quality Level

Partition	AQL	Definition
Major	0.65	Defects in Pattern Check (Display On)
Minor	1.0	Defects in Cosmetic Check (Display Off)

#### 6.2.1 EastRising Cosmetic Check (Display Off) in Non-Active Area

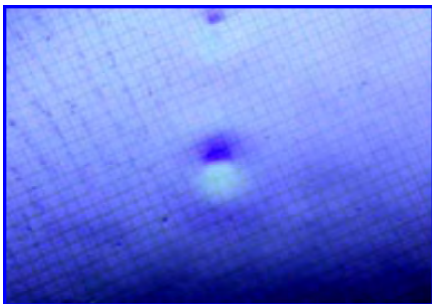
Check Item	Classification	Criteria
Panel General Chipping	Minor	<p><math>X &gt; 6\text{mm}</math> (Along with Edge)  <math>Y &gt; 1\text{mm}</math> (Perpendicular to edge)</p> 

6.2.2 EastRising Cosmetic Check (Display Off)in Non-Active Area (Continued)

Check Item	Classification	Criteria
Panel Crack	Minor	Any crack is not allowable 
Copper Exposed (Even Pin or Film)	Minor	Not Allowable by Naked Eye Inspection
Film or Trace Damage	Minor	
Termial Lead Prober Mark	Acceptable	
Glue or Contamination on Pin	Minor	
Ink marking on Back Side of Panel (Exclude on Film)	Acceptable	Ignore for Any

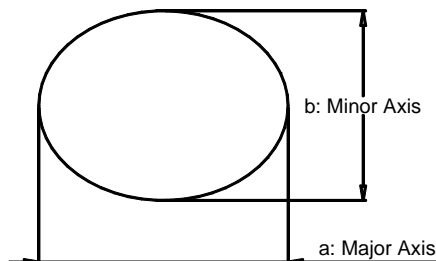
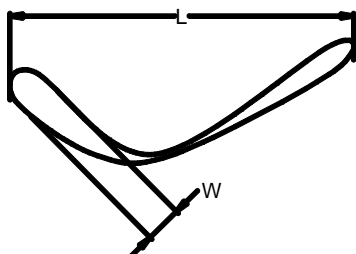
### 6.2.3 EastRising Cosmetic Check (Display Off) in Active Area

EastRising recommends to execute in clear environment (class 10k) if actual in necessary.

Check Item	Classification	Criteria
Any Dirt & Scratch on Polarizer's Protective Film	Acceptable	Ignore for not Affect the Polarizer
Scratches,Fiber,Line-Shape Defect (On Polarizer)	Minor	$W \leq 0.1$ Ignore $W > 0.1$ $L \leq 2$ $n \leq 1$ $L > 2$ $n = 0$
Dirt, Black Spot, Foreign Material (On Polarizer)	Minor	$\Phi \leq 0.1$ Ignore $0.1 < \Phi \leq 0.25$ $n \leq 1$ $0.25 < \Phi$ $n = 0$
Dent,Bubbles,White Spot (Any Transparent Spot on Polarizer)	Minor	$\Phi \leq 0.5$ Ignore if no Influence on Display $0.5 < \Phi$ $n = 0$ 
Fingerprint ,Flow Mark (On Polarizer)	Minor	Not Allowable


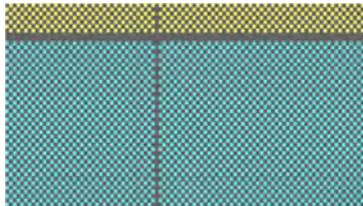
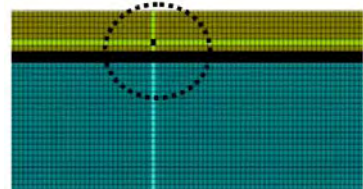
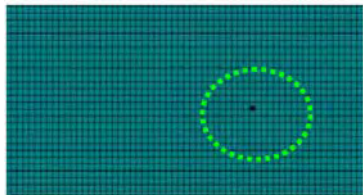
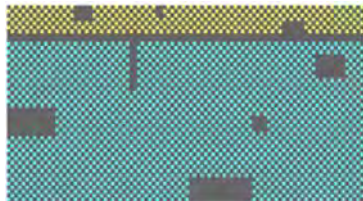

\* Protective film should not be tear off when cosmetic check.

\* Definition of W & L &  $\Phi$ (Unit:mm):  $\Phi = (a+b)/2$





6.2.4 EastRising Pattern Check (Display On) in Active Area

Check Item	Classification	Criteria
No Display	Major	
Missing Line	Major	
Pixel Short	Major	
Darker Pixel	Major	
Wrong Display	Major	
Un-uniform	Major	

## **7. PRECAUTIONS for USING**

### **7.1 Handling Precautions**

- 1) Since the EastRising OLED display panel is being made of glass, do not apply mechanical impacts such as dropping from a high position.
- 2) If the display panel is broken by some accident and the internal organic substance leaks out, be careful not to inhale nor lick the organic substance.
- 3) If pressure is applied to the display surface or its neighborhood of the EastRising OLED display module, the cell structure may be damaged and be careful not to apply pressure to these sections.
- 4) The polarizer covering the surface of the OLED display module is soft and easily scratched. Please be careful when handling the OLED display module.
- 5) When the surface of the polarizer of the OLED display module has soil, clean the surface. It takes advantage of by using following adhesion tape.
  - \* Scotch Mending Tape No. 810 or an equivalentNever try to breathe upon the soiled surface nor wipe the surface using cloth containing solvent such as ethyl alcohol, since the surface of the polarizer will become cloudy. Also, pay attention that the following liquid and solvent may spoil the polarizer:
  - \* Water
  - \* Ketone
  - \* Aromatic Solvents
- 6) Hold EastRising OLED display module very carefully when placing OLED display module into the system housing. Do not apply excessive stress or pressure to OLED display module. And, do not over bend the film with electrode pattern layouts. These stresses will influence the display performance. Also, secure sufficient rigidity for the outer cases.
- 7) Do not apply stress to the driver IC and the surrounding molded sections.
- 8) Do not disassemble nor modify the OLED display module.
- 9) Do not apply input signals while the logic power is off.
- 10) Pay sufficient attention to the working environments when handling EastRising OLED display modules to prevent occurrence of element breakage accidents by static electricity.
  - \* Be sure to make human body grounding when handling OLED display modules.
  - \* Be sure to ground tools to use or assembly such as soldering irons.
  - \* To suppress generation of static electricity, avoid carrying out assembly work under dry environments.

\* Protective film is being applied to the surface of the display panel of the OLED display module.  
Be careful since static electricity may be generated when exfoliating the protective film.

11) Protection film is being applied to the surface of the display panel and removes the protection film before assembling it. At this time, if the EastRising OLED display module has been stored for a long period of time, residue adhesive material of the protection film may remain on the surface of the display panel after removed of the film. In such case, remove the residue material by the method introduced in the above Section 5).

12) If electric current is applied when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful to avoid the above.

## 7.2 Storage Precautions

- 1) When storing EastRising OLED display modules, put them in static electricity preventive bags avoiding exposure neither to direct sun light nor to lights of fluorescent lamps. and, also, avoiding high temperature and high humidity environment or low temperature (less than 0℃) environments. (We recommend you to store these modules in the packaged state when they were shipped from EastRising.) At that time, be careful not to let water drops adhere to the packages or bags nor let dewing occur with them.
- 2) If electric current is applied when water drops are adhering to the surface of the OLED display module, when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful about the above.

## 7.3 Designing Precautions

- 1) The absolute maximum ratings are the ratings which cannot be exceeded for OLED display module, and if these values are exceeded, panel damage may be happen.
- 2) To prevent occurrence of malfunctioning by noise, pay attention to satisfy the VIL and VIH specifications and, at the same time, to make the signal line cable as short as possible.
- 3) We recommend you to install excess current preventive unit (fuses, etc.) to the power circuit (VDD). (Recommend value: 0.5A)
- 4) Pay sufficient attention to avoid occurrence of mutual noise interference with the neighboring devices.
- 5) As for EMI, take necessary measures on the equipment side basically.
- 6) When fastening the OLED display module, fasten the external plastic housing section.



- 7) If power supply to the EastRising OLED display module is forcibly shut down by such errors as taking out the main battery while the OLED display panel is in operation, we cannot guarantee the quality of this OLED display module.

#### 7.4 Precautions when disposing of the EastRising OLED display modules

- 1) Request the qualified companies to handle industrial wastes when disposing of the OLED display modules. Or, when burning them, be sure to observe the environmental and hygienic laws and regulations.

#### 7.5 Other Precautions

- 1) When an OLED display module is operated for a long of time with fixed pattern may remain as an after image or slight contrast deviation may occur. Nonetheless, if the operation is interrupted and left unused for a while, normal state can be restored. Also, there will be no problem in the reliability of the module.
- 2) To protect OLED display modules from performance drops by static electricity rapture, etc., do not touch the following sections whenever possible while handling the OLED display modules.
- \* Pins and electrodes
  - \* Pattern layouts such as the FPC
- 3) With this OLED display module, the OLED driver is being exposed. Generally speaking, semiconductor elements change their characteristics when light is radiated according to the principle of the solar battery. Consequently, if this OLED driver is exposed to light, malfunctioning may occur.
- \* Design the product and installation method so that the OLED driver may be shielded from light in actual usage.
  - \* Design the product and installation method so that the OLED driver may be shielded from light during the inspection processes.
- 4) Although this OLED display module stores the operation state data by the commands and the indication data, when excessive external noise, etc. enters into the module, the internal status may be changed. It therefore is necessary to take appropriate measures to suppress noise generation or to protect from influences of noise on the system design.
- 5) We recommend you to construct its software to make periodical refreshment of the operation statuses (re-setting of the commands and re-transference of the display data) to cope with catastrophic noise.

**That's the end of the datasheet.**